

WE CLAIM:

1. A printed circuit board (PCB) comprising:

a first layer of non-conductive material; and

5 a bond pad comprising a patterned conductive second material disposed upon said first layer said patterned bond pad defining a channel therein facilitating outgassing of bubbles via the channel.

2. The PCB as specified in Claim 1 wherein said bond pad is dimensioned to
10 render said pad non-planar.

3. The PCB as specified in Claim 1 wherein said bond pad is dimensioned to define a plurality of said channels extending laterally through said bond pad.

15 4. The PCB as specified in Claim 1 further comprising a plurality of pads disposed about said bond pad and being adapted to receive a multi-pin integrated circuit being centered over the bond pad.

5. The PCB as specified in Claim 3 wherein said channels are defined in a
20 radial pattern.

6. The PCB as specified in Claim 5 wherein said radial lines terminate at a point distant from a focal point.

5 7. The PCB as specified in Claim 6 wherein said radial lines have different lengths.

8. The PCB as specified in Claim 6 wherein some of the radial lines
10 terminate different distances from the focal point.

9. The PCB as specified in Claim 4 wherein said channels are defined as multiple lines.

15 10. The PCB as specified in Claim 9 wherein said channels are defined as parallel said lines.

11. The PCB as specified in Claim 9 wherein said multiple lines intersect.

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12. In combination;
an integrated circuit having a lower surface including an exposed solder
pad;
a first layer of non-conductive material; and
5 a bond pad opposed said contact pad and comprising a patterned
conductive second material disposed upon said first layer said patterned bond pad
defining a channel therein facilitating outgassing of bubbles via the channel.

10 13. The PCB as specified in Claim 12 wherein said bond pad is dimensioned
to render said pad non-planar.

14. The PCB as specified in Claim 12 wherein said bond pad is dimensioned
to define a plurality of said channels extending laterally through said bond pad.

15 15. The PCB as specified in Claim 12 wherein said channels are defined in a
radial pattern.

16. The PCB as specified in Claim 12 wherein said channels are defined as
multiple lines.

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17. A method of fabricating a printed circuit board (PCB) having electrically conductive signal traces thereon, comprising the steps of:

defining and patterning a bond pad to define a channel laterally through the bond pad adapted to facilitate outgassing of bubbles generated in solder during re-flow of solder upon the bond pad.

18. The method of fabricating as specified in Claim 17 wherein the bond pad is dimensioned to render the bond pad non-planar.

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